With the Bull Sequana X1000 range of supercomputers, Atos demonstrates its strategic commitment to the development of innovative high performance computing systems – the systems needed to meet the major challenges of the 21st century.

Designed by the Atos R&D in close cooperation with major customers, the Bull Sequana X1000 supercomputer leverages the latest technological advances, so as to guarantee maximum performance for a minimized operation cost. The race to exascale calls for technological breakthroughs. With Bull Sequana, Atos delivers an innovative solution that matches the exascale technological challenges.

Open for future technologies

Bull Sequana X1000 is highly modular, flexible and scalable. It is designed to support several types and several generations of compute nodes, equipped either with conventional processors or with accelerators. The following types of compute nodes will be introduced, as the corresponding processors become available:

- Intel® Xeon® processors E5 family (Broadwell-EP),
- Intel® Xeon® Phi™ (Knights Landing),
- Intel® Xeon® Processors scalable Family (Skylake SP) with faster memory interface
- Intel® Xeon® Processor Scalable Family (Skylake SP) + NVidia® Pascal GPUs,
- Sequana X1000 supports fast state-of-the-art interconnects, such as:
  - Bull eXascale Interconnect (BXI),
  - InfiniBand EDR.

The Bull Sequana cell

In Bull Sequana the computing resources are grouped into cells. Each cell tightly integrates:
- compute nodes,
- interconnect switches,
- redundant power supply units,
- redundant liquid cooling heat exchangers,
- a dual node for distributed management and diskless support.

This packaging consisting of large building blocks facilitates high-scale deployment - up to 64,000 nodes, and optimizes density, scalability and cost-effectiveness.

The Bull Sequana X1000 cell is organized across three cabinets.
- the two side cabinets contain compute nodes,
- the central cabinet houses the interconnect switches.

Limiting energy consumption

Controlling energy consumption is the main roadblock on the path to exascale. Sequana is ultra energy-efficient: it targets a PUE very close to 1.

100% of the components of Bull Sequana - both compute nodes and switches - are cooled using an enhanced version of the Bull patented Direct Liquid Cooling (DLC) solution. DLC is a proven cooling technology that minimizes the global energy consumption of a system by using warm water up to 40°C.

The cooling system of Sequana X1000 is sized to evacuate the heat generated even by the most extreme configurations - with very powerful and energy-hungry nodes.

Unchanged serviceability

For easy maintenance, all Sequana X1000 components (compute nodes, interconnect switches, PSUs, heat exchangers…) are hot-swappable and can be serviced without interrupting system production. In the compute blades, the processors and DIMMs can be replaced without removing the cold plate.

In a Sequana X1000 cell, all maintenance operations are just as easy as in a standard air-cooled system.

Trusted partner for your Digital Journey
The Bull Sequana X1000 cell

There are two types of compute cabinets:
- The base compute cabinet provides liquid cooling to the compute blades it houses and also to the switch cabinet.
- The extension compute cabinet is optional and has its own cooling sub-system.

Three types of interfaces connect the compute and switch cabinets together:
- Liquid interface with two flexible pipes from Base compute cabinet hydraulic chassis to switch cabinet manifolds.
- Interconnect interface: each node is connected through one or two interconnect links, one per NIC.
- Management interface for all management controllers in the compute cabinet (PMC, BMC, HMC): one 1Gb/s Ethernet link per node plus 4 sidebands signals for platform management.

The compute nodes are connected to the switch cabinet (L1 switches) via 12 copper cable octopuses named:
- Sideplane Octopus Double for 2 NICs per node,
- Sideplane Octopus Single for 1 NIC per node.

Each Bull Sequana X1000 compute cabinet houses 48 horizontal compute blades, with the associated power modules at the top of the cabinet and the redundant hydraulic modules for cooling at the bottom of the cabinet.

24 blades are mounted on the front side of the cabinet, while the 24 other blades are mounted on the rear side.

Each 1U blade contains three compute nodes, except for GPU-based blades which contain one node.

Each cell can therefore contain up to:
- 288 dual-socket Intel® Xeon® nodes OR,
- 288 single-socket Intel® Xeon Phi™ nodes OR,
- 96 dual-socket Intel® Xeon® nodes with 4 Nvidia® Pascal GPUs.

Dimensions/Weight

- Mounting Capacity: 42U
- Size (HxWxD) without UCM: 2020x750x1270 mm - With UCM (max): 2400x750x1270 mm
- Weight without compute blade: 1000 kg - Packing weight (without compute blade, with pallet): 1110 kg
- Total weight of cabinet on slab floor (fully equipped): 2200 Kg (2300Kg with UCM)

Compute Power Group

- 75 U form factor at the top of the cabinet
  - Up to 4 x 15KW air cooling PSU shelves at the front of the cabinet with at PSU level (N+X)
  - Up to 4 x 15KW air cooling PSU shelves at the rear of the cabinet with at PSU level (N+X)
  - 1 Power Management Controller Module
  - 2 x 2 64A tri-phased 400V AC EU input power lines or 2 x 4) 64A tri-phased 600V AC US input power lines
  - Option: 2 Ultra Capacity Module chassis supporting power outage of 300ms at full load or 800ms at 45% load in case of a 2 or 3 phases AC power outage
- Ready to support liquid cooling PSU shelf in Q3 2017 (FCS TBC).
The Bull Sequana X1000 series

Switch cabinet

The central Bull Sequana X1000 switch cabinet houses:
- two levels of interconnect switches in full fat-tree topology,
- their associated DC power generator (SWPG: SWitch Power Group) and
- management components such as Ethernet switches and one redundant server for Island management and administration (ISMA).

The switch cabinet provides internal connections (within the cell) through copper cables and external connections through optical cables.

288 external ports are available to interconnect each cell with the rest of the system to form different topologies, such as Fat-tree, All-to-all or other directly connected configurations.

External nodes (such as for example input/output gateways, services nodes…) can be plugged into the L1 switches replacing compute nodes.

Dimensions /Weight
Mounting capacity: 42U - Size (HxWxD) without UCM: 2020x600x1270 mm - With UCM (max): ~2400x600x1270mm
Weight on castors w/ SW & W/o UCM: up to 745 kg - Packing weight (with pallet) w/ SW & W/o UCM: up to 800 kg
Total weight of cabinet on slab floor (fully equipped & W/ UCM): up to 810 kg

L1 switches
- Up to 24 BXI Direct Liquid Cooled switches (48 ports module in 1U format):
  - without optical ports and with a 1 Gb/s/s Ethernet switch
  - or with 3 optical ports and with a 1 Gb/s/s Ethernet switch
- OR up to 12 InfiniBand EDR 36 ports Direct Liquid Cooled modules in 1U format:
  - without optical ports and with a 1 Gb/s/s Ethernet switch
  - or with 3 optical ports and with a 1 Gb/s/s Ethernet switch

L2 switches
- Up to 12 1U L2 Direct Liquid Cooled switch Modules with two 48 ports BXI L2 switches per module
- OR up to 12 1U L2 Direct Liquid Cooled switch Modules with one 36 ports IB EDR L2 switch per module

Interconnect between L1 & L2 switch
- Backplane Octopus Double (BOD) providing all-to-all connections between 24 L1 switch modules and 12 L2 switch modules (24 L1 switches) for configurations with 2 NIC per compute node
- Backplane Octopus Single (BOS) providing all-to-all connections between 12 L1 switch modules and 6 L2 switch modules (12 L2 switches) for configurations with 1 NIC per compute node
The management backplane implements the Ethernet and sideband management connections between L1/L2/Leaf/Top switch modules with:
- A Backplane Octopus Management Base (BOMB) that connects left L2 switches
- A Backplane Octopus Management Extension (BOME) that connects right L2 switches

Island Monitoring and Administration
- Up to 2 x 24 ports 1Gb/s Ethernet Leaf switch Management Modules in 1U format
- Up to 2 x Ethernet Top switch Management Modules in 1U format
Each switch provides 24 downlink 1Gb/s Ethernet ports and 4 uplink 10 Gb/s Ethernet ports.
- 2U Island Monitoring and Administration (ISMA) built with 2 redundant servers

Switch Power Group
- 2 air-cooled PSU shelves (1+1 redundancy) with 4 Power supply Units (PSU) of 3kW
- 1 Power Distribution unit (PDU) with 2 x 32A tri-phased 230/400Vac input power lines
- Power Management Controller Module
- Option: Ultra Capacity Modules to support an AC power outage of up to 900ms at full load
Ready to support liquid cooling PSU shelf in Q3 2017 (FCS TBC)

Regulatory compliance
Safety (EC, IEC, UL, CSA certifications); Electromagnetic Compatibility (EC, FCC, ICES-03, VCCI certifications); Environment (RoHS II & WEEE directives, REACH regulation)

Warranty
Standard warranty: 1 year - Extended Warranty: consult us
Compute blades

In each 1U blade, a cold plate with active liquid flow cools all hot components by direct contact – the Bull Sequana compute blades contain no fan.

The following compute blades are initially available:

- The 1U Bull Sequana X1110 blade integrates 3 compute nodes, each powered by 2 Intel® Xeon® E5-2600 V4 processors (code named Broadwell-EP).
- The 1U Bull Sequana X1120 blade integrates 3 compute nodes, each powered by 2 Intel® Xeon® Processor Scalable Family (Skylake SP).
- The 1U Bull Sequana X1125 blade includes a 2 Intel® Xeon® Processor Scalable Family (Skylake SP) compute node equipped with 4 NVIDIA® Tesla Pascal P100 16GB GPUs.

<table>
<thead>
<tr>
<th>Bull Sequana X1110 blade</th>
<th>Bull Sequana X1210 blade</th>
<th>Bull Sequana X1120 blade</th>
<th>Bull Sequana X1125 GPU blade</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Design</strong></td>
<td><strong>Processors</strong></td>
<td><strong>Architecture</strong></td>
<td><strong>Memory</strong></td>
</tr>
<tr>
<td>1U blade comprising 3 compute nodes side-by-side</td>
<td>3 x 2 Intel® Xeon® E5-2600 v4 processors</td>
<td>3 x 1 Intel® C610 chipset</td>
<td>3 x 6 DDR4 memory slots (max 256 GB with 32 GB DIMMs)</td>
</tr>
<tr>
<td><strong>Processors</strong></td>
<td><strong>Architecture</strong></td>
<td><strong>Memory</strong></td>
<td><strong>I/O slots</strong></td>
</tr>
<tr>
<td>3 x 1 Intel® Xeon® Phi™ KNL processor</td>
<td>3 x 1 Intel® C610 chipset</td>
<td>3 x 12 DDR4 memory slots (max 384 GB with 32 GB DIMMs)</td>
<td>InfiniBand EDR 1 port mezzanine board or BXI 1 or 2 ports mezzanine board</td>
</tr>
<tr>
<td><strong>Architecture</strong></td>
<td><strong>Memory</strong></td>
<td><strong>I/O slots</strong></td>
<td><strong>Storage</strong></td>
</tr>
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<td>3 x 1 optional SATA SSD drive</td>
</tr>
<tr>
<td><strong>Memory</strong></td>
<td><strong>Power supply</strong></td>
<td><strong>Storage</strong></td>
<td><strong>Power supply</strong></td>
</tr>
<tr>
<td>3 x 8 DDR4 memory slots (max 192 GB with 32 GB DIMMs)</td>
<td>In cabinet</td>
<td>3 x 1 optional SATA SSD drive</td>
<td>In cabinet</td>
</tr>
<tr>
<td><strong>I/O slots</strong></td>
<td><strong>Cooling</strong></td>
<td><strong>Storage</strong></td>
<td><strong>Cooling</strong></td>
</tr>
<tr>
<td>InfiniBand EDR 1 port mezzanine board or BXI 1 or 2 ports mezzanine board</td>
<td>Cooling by direct contact with DLC coldplate or through heat spreaders for DIMMS</td>
<td>3 x 1 optional SATA drive via PCIe switch</td>
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</tr>
<tr>
<td><strong>Storage</strong></td>
<td><strong>Physical specifications</strong></td>
<td><strong>Power supply</strong></td>
<td><strong>Physical specifications</strong></td>
</tr>
<tr>
<td>3 x 1 optional SATA drive</td>
<td>4445 x 600 x 540 mm (H x W x D)</td>
<td>In cabinet</td>
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</tr>
<tr>
<td><strong>Power supply</strong></td>
<td><strong>OS and software</strong></td>
<td><strong>Warranty</strong></td>
<td><strong>OS and software</strong></td>
</tr>
<tr>
<td>In cabinet</td>
<td>Red Hat Enterprise Linux &amp; Bull Supercomputer Suite support</td>
<td>Standard warranty: 1 year - Extended warranty: consult us</td>
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</tr>
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<td><strong>Warranty</strong></td>
<td><strong>Regulatory compliance</strong></td>
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